

Thursday 25 May

11:00

A11: Instrument II

Session | Location: Ballroom 3 | Conveners: Prof. Chatchawal Wongchoosuk, Prof. Wiwat Wongkokua

11:00-11:15

Optimization parameters of installation automatic die bonding machine for integrated circuit packaging

Speaker

Mr Tanatpol Nanthavittayaporn

11:15-11:30

The prototype of high stiffness load cell for Rockwell hardness testing machine calibration according to ISO 6508-2:2015.

Speaker

Dr Montree PAKKRATOKE

11:30-11:45 The development of 1-D nest bar measurement system

Speaker

Dr Narin Chantawong

11:45-12:00

Preliminary of spindle axial and angular motions measurement using plane mirror interferometer

Speaker

Muhummad Madden

12:00-12:15

Design and Implementation of a Measurement System for Inspection of Magnetic **Force Microscopy Probes**

Speaker

Mr Natthawat Phanchat

12:15